

# SL2S2002; SL2S2102

## ICODE SLIX

Rev. 3.3 — 23 August 2012  
178033

Product data sheet  
COMPANY PUBLIC

## 1. General description

---

The ICODE SLIX IC is a dedicated chip for intelligent label applications such as libraries, product authentication in different industries such as pharmaceutical, medical devices and alcohol, as well as production management in different areas of the industry. This IC is the third generation of a product family of smart label ICs based on the ISO standards ISO/IEC 15693 ([Ref. 1](#)) and ISO/IEC 18000-3 ([Ref. 4](#)), prolonging a successful story of NXP in the field of vicinity identification systems.

The ICODE system offers the possibility of operating labels simultaneously in the field of the reader antenna (anticollision). It is designed for long range applications.

### 1.1 Contactless energy and data transfer

Whenever connected to a very simple and easy-to-produce type of antenna (as a result of the 13.56 MHz carrier frequency) made out of a few windings printed, wound, etched or punched coil, the ICODE SLIX IC can be operated without line of sight up to a distance of 1.5 m (gate width). No battery is needed. When the smart label is positioned in the field of an interrogator antenna, the high speed RF communication interface enables data to be transmitted up to 53 kbit/s.

### 1.2 Anticollision

An intelligent anticollision function enables several tags to operate in the field simultaneously. The anticollision algorithm selects each tag individually and ensures that the execution of a transaction with a selected tag is performed correctly without data corruption resulting from other tags in the field.

### 1.3 Security and privacy aspects

- Unique Identifier (UID):  
The UID cannot be altered and guarantees the uniqueness of each label.
- Password protected EAS and AFI functionality:  
The 32-bit EAS/AFI password enables the addressed label to be set in a mode where the EAS status and the AFI value can only be changed if the correct EAS/AFI password is transmitted to the label within the mentioned commands.



## 2. Features and benefits

---

### 2.1 ICODE SLIX RF interface (ISO/IEC 15693)

- Contactless transmission of data and supply energy (no battery needed)
- Operating distance: up to 1.5 m (depending on antenna geometry)
- Operating frequency: 13.56 MHz (ISM, world-wide licence freely available)
- Fast data transfer: up to 53 kbit/s
- High data integrity: 16-bit CRC, framing
- True anticollision
- Password protected Electronic Article Surveillance (EAS)
- Password protected Application Family Identifier (AFI)
- Data Storage Format Identifier (DSFID)
- Additional fast anticollision read
- Write distance equal to read distance

### 2.2 EEPROM

- 1024 bits, organized in 32 blocks of 4 bytes each
- 50 years data retention
- Write endurance of 100000 cycles

### 2.3 Security

- Unique identifier for each device
- Lock mechanism for each user memory block (write protection)
- Lock mechanism for DSFID, AFI, EAS
- Password (32-bit) protected EAS and AFI functionality

## 3. Applications

---

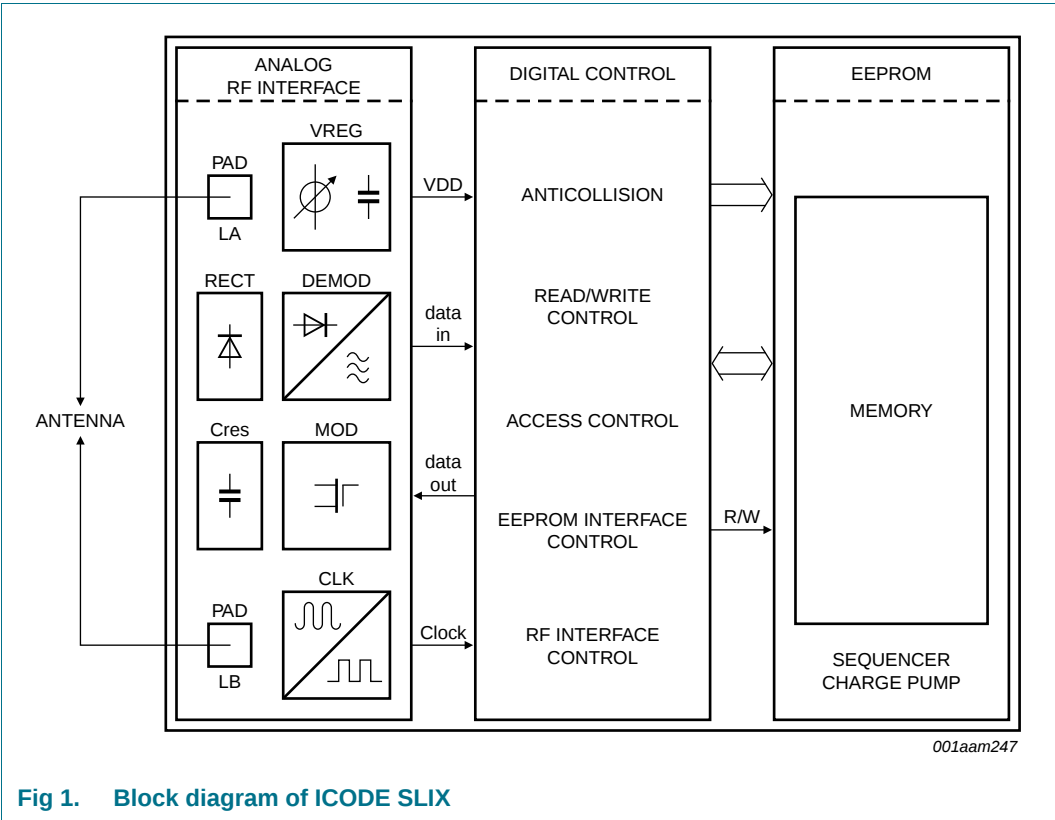
- Libraries
- Item level tagging in pharmaceutical supply chains
- Counterfeit protection for consumer goods
- Industrial applications
- Asset and document tracking

4. Ordering information

Table 1. Ordering information

| Type number | Package |                                                                                                                                                   | Version |
|-------------|---------|---------------------------------------------------------------------------------------------------------------------------------------------------|---------|
|             | Name    | Description                                                                                                                                       |         |
| SL2S2002FUD | wafer   | sawn, bumped wafer, 120 μm, on film frame carrier, C <sub>i</sub> between LA and LB = 23.5 pF (typical)                                           | -       |
| SL2S2102FUD | wafer   | sawn, bumped wafer, 120 μm, on film frame carrier, C <sub>i</sub> between LA and LB = 97 pF (typical)                                             | -       |
| SL2S2002FTB | XSON3   | plastic extremely thin small outline package; no leads; 3 terminals; body 1 x 1.45 x 0.5 mm; C <sub>i</sub> between LA and LB = 23.5 pF (typical) | SOT1122 |
| SL2S2102FTB | XSON3   | plastic extremely thin small outline package; no leads; 3 terminals; body 1 x 1.45 x 0.5 mm; C <sub>i</sub> between LA and LB = 97 pF (typical)   | SOT1122 |

5. Block diagram



6. Pinning information

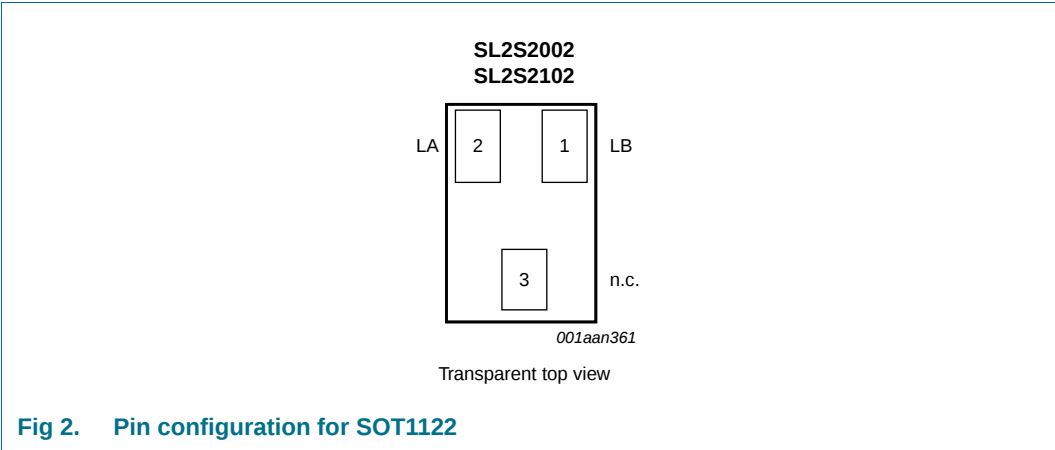
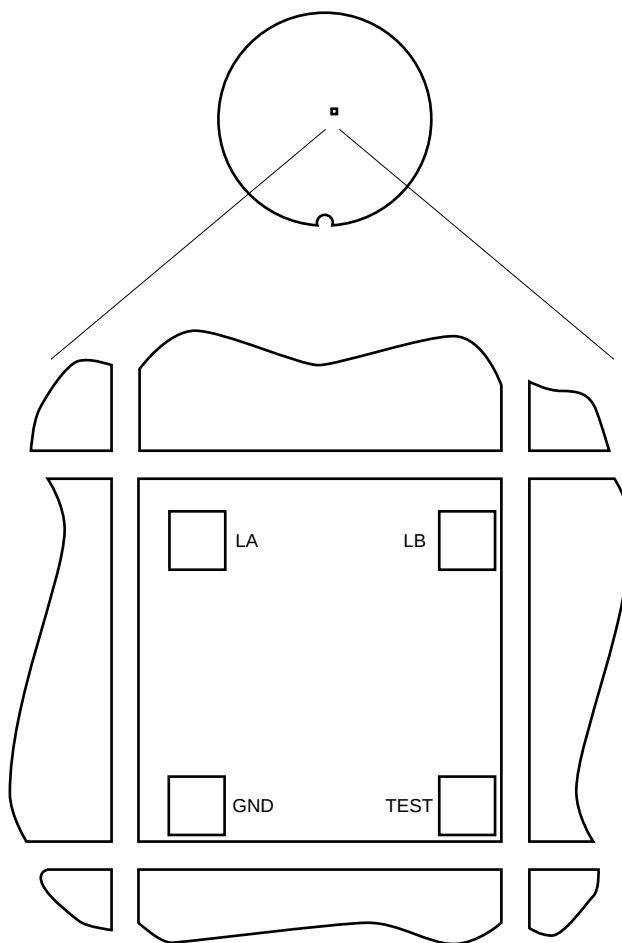


Table 2. Pin description SOT1122

| Pin | Symbol | Description      |
|-----|--------|------------------|
| 1   | LB     | antenna RF input |
| 2   | LA     | antenna RF input |
| 3   | n.c.   | not connected    |

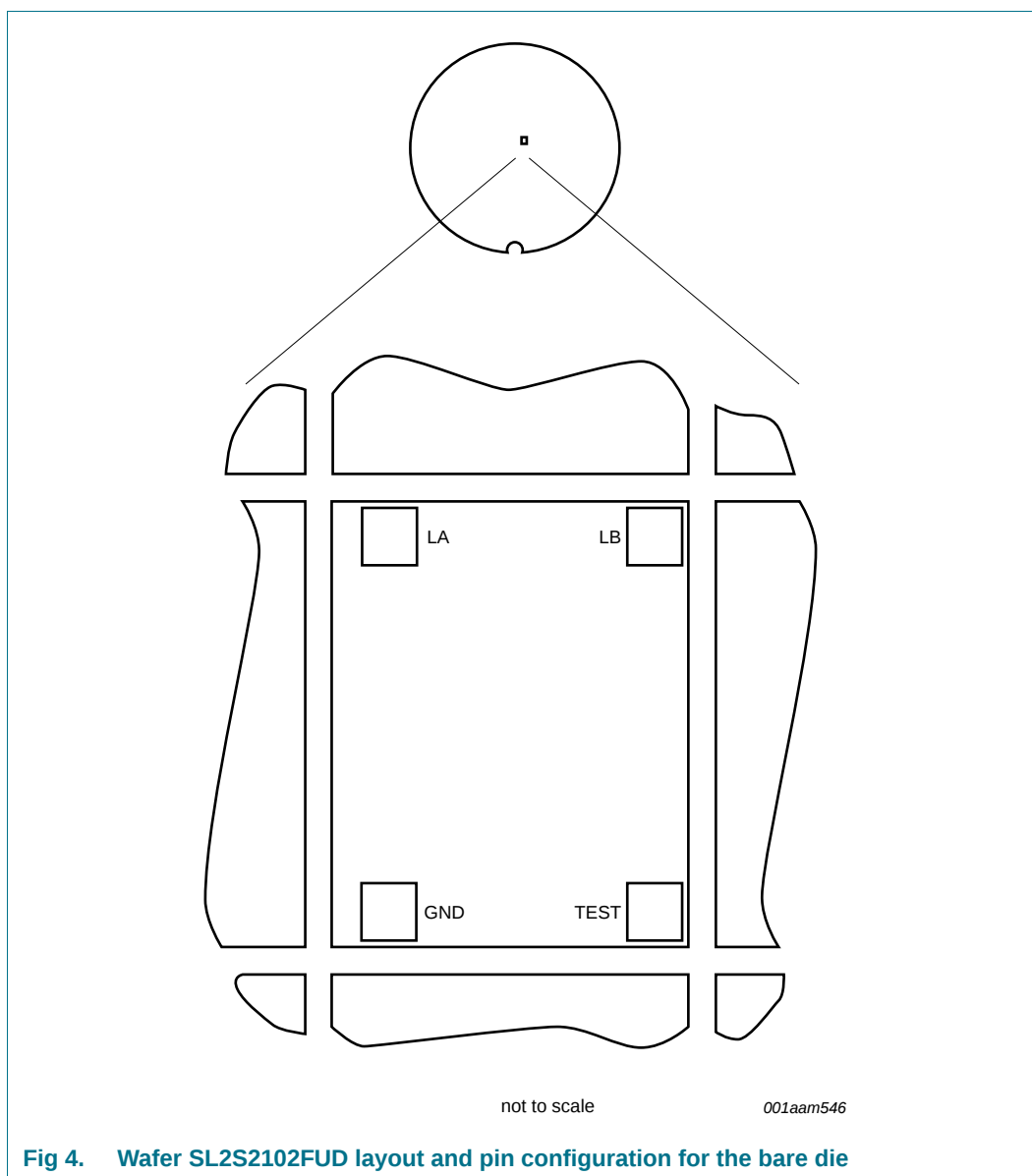
## 7. Wafer layout



not to scale

001aam246

**Fig 3. Wafer SL2S2002FUD layout and pin configuration for the bare die**



## 7.1 Bonding pad description

**Table 3. Bonding pad description**

| Symbol | Description      |
|--------|------------------|
| LA     | antenna RF input |
| LB     | antenna RF input |
| GND    | ground           |
| TEST   | test input       |

## 8. Mechanical specification

### 8.1 Wafer specification

See [Ref. 6 "General specification for 8" wafer on UV-tape with electronic fail die marking"](#).

**Table 4. Wafer specification**

|                                |                                                                      |
|--------------------------------|----------------------------------------------------------------------|
| <b>Wafer</b>                   |                                                                      |
| Designation                    | each wafer is enscribed with batch number and wafer number           |
| Diameter                       | 200 mm (8 inches)                                                    |
| Thickness                      | 120 $\mu\text{m} \pm 15 \mu\text{m}$                                 |
| Process                        | CMOS 0.14 $\mu\text{m}$                                              |
| Batch size                     | 25 wafers                                                            |
| Dies per wafer                 |                                                                      |
| SL2S2002FUD                    | 110050                                                               |
| SL2S2102FUD                    | 88225                                                                |
| <b>Wafer backside</b>          |                                                                      |
| Material                       | Si                                                                   |
| Treatment                      | ground and stress release                                            |
| Roughness                      | $R_a$ minimum = 0.5 $\mu\text{m}$<br>$R_t$ maximum = 5 $\mu\text{m}$ |
| <b>Chip dimensions</b>         |                                                                      |
| Die size without scribe        |                                                                      |
| SL2S2002FUD                    | 520 $\mu\text{m} \times 484 \mu\text{m} = 251680 \text{ mm}^2$       |
| SL2S2102FUD                    | 520 $\mu\text{m} \times 607 \mu\text{m} = 315640 \text{ mm}^2$       |
| Scribe line width              |                                                                      |
| X-dimension                    | 15 $\mu\text{m}$ (scribe line width measured between nitride edges)  |
| Y-dimension                    | 15 $\mu\text{m}$ (scribe line width measured between nitride edges)  |
| Number of pads                 | 4                                                                    |
| Pad location                   | non-diagonal/placed in chip corners                                  |
| Distance pad to pad LA to LB   | 400 $\mu\text{m}$                                                    |
| Distance pad to pad LB to TEST |                                                                      |
| SL2S2002FUD                    | 360 $\mu\text{m}$                                                    |
| SL2S2102FUD                    | 517 $\mu\text{m}$                                                    |
| <b>Passivation on front</b>    |                                                                      |
| Type                           | sandwich structure                                                   |
| Material                       | PE-nitride (on top)                                                  |
| Thickness                      | 1.75 $\mu\text{m}$ total thickness of passivation                    |
| <b>Au bump</b>                 |                                                                      |
| Material                       | >99.9 % pure Au                                                      |
| Hardness                       | 35 HV to 80 HV 0.005                                                 |
| Shear strength                 | >70 MPa                                                              |
| Height                         | 18 $\mu\text{m}$                                                     |
| Height uniformity              |                                                                      |

**Table 4. Wafer specification**

|                          |                                          |
|--------------------------|------------------------------------------|
| within a die             | $\pm 2\ \mu\text{m}$                     |
| within a wafer           | $\pm 3\ \mu\text{m}$                     |
| wafer to wafer           | $\pm 4\ \mu\text{m}$                     |
| Bump flatness            | $\pm 1.5\ \mu\text{m}$                   |
| Bump size                |                                          |
| LA, LB                   | $60\ \mu\text{m} \times 60\ \mu\text{m}$ |
| TEST, GND                | $60\ \mu\text{m} \times 60\ \mu\text{m}$ |
| variation                | $\pm 5\ \mu\text{m}$                     |
| Under bump metallization | sputtered TiW                            |

### 8.1.1 Fail die identification

No inkdots are applied to the wafer.

Electronic wafer mapping (SECS II format) covers the electrical test results and additionally the results of mechanical/visual inspection.

See [Ref. 6 "General specification for 8" wafer on UV-tape with electronic fail die marking"](#).

### 8.1.2 Map file distribution

See [Ref. 6 "General specification for 8" wafer on UV-tape with electronic fail die marking"](#).

## 9. Functional description

### 9.1 Block description

The ICODE SLIX IC consists of three major blocks:

- Analog RF interface
- Digital controller
- EEPROM

The analog section provides stable supply voltage and demodulates data received from the reader for processing by the digital section. The analog section's modulation transistor also transmits data back to the reader.

The digital section includes the state machines, processes the protocol and handles communication with the EEPROM.

The label requires no internal power supply. Its contactless interface generates the power supply and the system clock via the resonant circuitry by inductive coupling to the interrogator. The interface also demodulates data that are transmitted from the interrogator to the ICODE Label, and modulates the electromagnetic field for data transmission from the ICODE Label to the interrogator.

Data are stored in a non-volatile memory (EEPROM).

### 9.2 Memory organization

The 1024 bit EEPROM memory is divided into 32 blocks. A block is the smallest access unit. Each block consists of 4 bytes (1 block = 32 bits). Bit 0 in each byte represents the least significant bit (LSB) and bit 7 the most significant bit (MSB), respectively.

The memory is divided into 2 parts:

- Configuration area  
Within this part of the memory all required information is stored, such as UID, write protection, access control information, passwords, AFI and EAS. This memory area cannot be directly accessed.
- User memory  
Within the 896 bit memory area the user data are stored. Direct read/write access to this part of the memory is possible depending on the related write protection conditions.

Table 5. Memory organization

| Block | Byte 0 | Byte 1 | Byte 2 | Byte 3 | Description                                                        |
|-------|--------|--------|--------|--------|--------------------------------------------------------------------|
|       |        |        |        |        | Configuration area for internal use                                |
| 0     |        |        |        |        | User memory:<br>28 blocks,<br>4 bytes each,<br>112 bytes in total. |
| 1     |        |        |        |        |                                                                    |
| 2     |        |        |        |        |                                                                    |
| :     | :      | :      | :      | :      |                                                                    |
| 25    |        |        |        |        |                                                                    |
| 26    |        |        |        |        |                                                                    |
| 27    |        |        |        |        |                                                                    |

Blocks 0 to 27 can be addressed with read and write commands only.

### 9.2.1 Unique identifier

The 64-bit unique identifier (UID) is programmed during the production process according to ISO/IEC 15693-3 and cannot be changed afterwards.

The 64 bits are numbered according to ISO/IEC 15693-3 starting with LSB 1 and ending with MSB 64. This is in contrast to the general used bit numbering within a byte.

The TAG type is a part of the UID (bit 41 to 48, next to the manufacturer code which is "04h" for NXP Semiconductors).

The TAG type of the ICODE SLIX IC is "01h".

Bit 37 is set to logic 1 for the ICODE SLIX IC which indicates that this type supports the password protected EAS/AFI feature (not supported by ICODE SLI SL2ICS2001 with bit 37 set to logic 0).

Table 6. Unique identifier

| MSB   |       |       |                               |       |       | LSB   |       |
|-------|-------|-------|-------------------------------|-------|-------|-------|-------|
| 64:57 | 56:49 | 48:41 | 40:1                          |       |       |       |       |
| "E0"  | "04"  | "01"  | IC manufacturer serial number |       |       |       |       |
| UID 7 | UID 6 | UID 5 | UID 4                         | UID 3 | UID 2 | UID 1 | UID 0 |

### 9.2.2 Configuration of delivered ICs

ICODE SLIX ICs are delivered with the following configuration by NXP Semiconductors:

- Unique identifier is unique and read only
- Write access conditions allow change to user blocks, AFI, DSFID, EAS and passwords
- Status of EAS mode is not defined
- AFI is supported and not defined
- All EAS/AFI password bytes are 00h
- EAS and AFI password protection is disabled
- DSFID is supported and not defined
- User data memory is not defined

**Remark:** Because the EAS mode is undefined at delivery, the EAS mode shall be set (enabled or disabled) according to your application requirements during the test or initialization phase.

**Remark:** If EAS and/or AFI password protection is not required in the targeted application, it is recommended a random EAS/AFI password is written during the label initialization.

## 9.3 Communication principle

For detailed description of the protocol and timing please refer to ISO/IEC 15693-2 (modulation, bit-coding, framing, [Ref. 2](#)) and ISO/IEC 15693-3 (anticollision, timing, protocol, [Ref. 3](#)).

## 9.4 Supported commands

### 9.4.1 Mandatory commands

#### 9.4.1.1 INVENTORY

As defined in ISO/IEC 15693-3.

#### 9.4.1.2 STAY QUIET

As defined in ISO/IEC 15693-3.

## 9.4.2 Optional commands

### 9.4.2.1 READ SINGLE BLOCK

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

### 9.4.2.2 WRITE SINGLE BLOCK

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

### 9.4.2.3 LOCK BLOCK

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

### 9.4.2.4 READ MULTIPLE BLOCKS

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

**Remark:** If the sum of the first block number and the number of blocks exceeds the total available number of user blocks, the number of transmitted blocks is less than the requested number of blocks, which means that the last returned block is the highest available user block, followed by the 16-bit CRC and the EOF.

### 9.4.2.5 SELECT

As defined in ISO/IEC 15693-3.

### 9.4.2.6 RESET TO READY

As defined in ISO/IEC 15693-3.

### 9.4.2.7 WRITE AFI

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

**Remark:** This command maybe password protected, refer to [Section 9.4.3.11](#) "PASSWORD PROTECT EAS/AFI".

#### 9.4.2.8 LOCK AFI

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

**Remark:** This command maybe password protected, refer to [Section 9.4.3.11](#) "PASSWORD PROTECT EAS/AFI".

#### 9.4.2.9 WRITE DSFID

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

#### 9.4.2.10 LOCK DSFID

As defined in ISO/IEC 15693-3.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

#### 9.4.2.11 GET SYSTEM INFORMATION

As defined in ISO/IEC 15693-3.

The TAG type of the ICODE SLIX is "01h".

#### 9.4.2.12 GET MULTIPLE BLOCK SECURITY STATUS

As defined in ISO/IEC 15693-3.

**Remark:** If the sum of the first block number and the number of blocks exceeds the total available number of user blocks the number of transmitted security status bytes is less than the requested number, which means that the last returned status byte is the one corresponding to the highest available user block, followed by the 16-bit CRC and the EOF.

### 9.4.3 Custom commands

The manufacturer code of NXP Semiconductors is defined in ISO/IEC 7816-6A1 ([Ref. 5](#)). It has the value "04h".

For the structure of custom commands please refer to ISO/IEC 15693-3.

If not explicitly specified differently all address modes are supported.

#### 9.4.3.1 GET RANDOM NUMBER

**Command code = B2h**

The GET RANDOM NUMBER command is required to receive a random number from the label IC. The passwords that will be transmitted with the SET PASSWORD command have to be calculated with the password and the random number (see [Section 9.4.3.2](#) "SET PASSWORD").

The different passwords are addressed with the password identifier.

**Table 7. Request format**

| SOF | Flags  | GET<br>RANDOM<br>NUMBER | IC Mfg<br>code | UID                 | CRC16   | EOF |
|-----|--------|-------------------------|----------------|---------------------|---------|-----|
| -   | 8 bits | 8 bits                  | 8 bits         | 64 bits<br>optional | 16 bits | -   |

**Table 8. Response format when Error\_flag set**

| SOF | Flags  | Error code | CRC16   | EOF |
|-----|--------|------------|---------|-----|
| -   | 8 bits | 8 bits     | 16 bits | -   |

**Table 9. Response format when Error\_flag NOT set**

| SOF | Flags  | Random number | CRC16   | EOF |
|-----|--------|---------------|---------|-----|
| -   | 8 bits | 16 bits       | 16 bits | -   |

#### 9.4.3.2 SET PASSWORD

**Command code = B3h**

The SET PASSWORD command enables the EAS/AFI password to be transmitted to the label to access EAS and/or AFI (if the EAS and/or AFI password is enabled). The SET PASSWORD command has to be executed just once for the related password if the label is powered.

**Remark:** The SET PASSWORD command can only be executed in Addressed or Selected mode.

The XOR password has to be calculated with the password and two times the received random number from the last GET RANDOM NUMBER command:

$\text{XOR\_Password}[31:0] = \text{Password}[31:0] \text{ XOR } \{\text{Random\_Number}[15:0], \text{Random\_Number}[15:0]\}.$

The EAS/AFI password is addressed with the password identifier.

**Table 10. Request format**

| SOF | Flags  | SET<br>PASSWORD | IC Mfg<br>code | UID                 | Password<br>identifier | XOR<br>password | CRC16   | EOF |
|-----|--------|-----------------|----------------|---------------------|------------------------|-----------------|---------|-----|
| -   | 8 bits | 8 bits          | 8 bits         | 64 bits<br>optional | 8 bits                 | 32 bits         | 16 bits | -   |

**Table 11. Password Identifier**

| Password identifier | Password |
|---------------------|----------|
| 10h                 | EAS/AFI  |

**Table 12. Response format when Error\_flag set**

| SOF | Flags  | Error code | CRC16   | EOF |
|-----|--------|------------|---------|-----|
| -   | 8 bits | 8 bits     | 16 bits | -   |

**Table 13. Response format when Error\_flag NOT set**

| SOF | Flags  | CRC16   | EOF |
|-----|--------|---------|-----|
| -   | 8 bits | 16 bits | -   |

**Remark:** If the IC receives an invalid password, it will not execute any following command until a Power-On Reset (POR) (RF reset) is executed.

#### 9.4.3.3 WRITE PASSWORD

**Command code = B4h**

The WRITE PASSWORD command enables a new password to be written into the related memory if the related old password has already been transmitted with a SET PASSWORD command and the addressed password is not locked (see [Section 9.4.3.4 "LOCK PASSWORD"](#)).

**Remark:** The WRITE PASSWORD command can only be executed in addressed or selected mode. The new password takes effect immediately which means that the new password has to be transmitted with the SET PASSWORD command to access protected blocks.

The EAS/AFI password is addressed with the password identifier.

The timing of the command is write alike.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

**Table 14. Request format**

| SOF | Flags  | WRITE PASSWORD | IC Mfg code | UID              | Password identifier | Password | CRC16   | EOF |
|-----|--------|----------------|-------------|------------------|---------------------|----------|---------|-----|
| -   | 8 bits | 8 bits         | 8 bits      | 64 bits optional | 8 bits              | 32 bits  | 16 bits | -   |

**Table 15. Password identifier**

| Password identifier | Password |
|---------------------|----------|
| 10h                 | EAS/AFI  |

**Table 16. Response format when Error\_flag set**

| SOF | Flags  | Error code | CRC16   | EOF |
|-----|--------|------------|---------|-----|
| -   | 8 bits | 8 bits     | 16 bits | -   |

**Table 17. Response format when Error\_flag NOT set**

| SOF | Flags  | CRC16   | EOF |
|-----|--------|---------|-----|
| -   | 8 bits | 16 bits | -   |

#### 9.4.3.4 LOCK PASSWORD

**Command code = B5h**

The LOCK PASSWORD command enables the addressed password to be locked if the related password has already been transmitted with a SET PASSWORD command. A locked password cannot be changed.

The EAS/AFI password is addressed with the password identifier.

The timing of the command is write alike.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

**Table 18. Request format**

| SOF | Flags  | LOCK PASSWORD | IC Mfg code | UID              | Password identifier | CRC16   | EOF |
|-----|--------|---------------|-------------|------------------|---------------------|---------|-----|
| -   | 8 bits | 8 bits        | 8 bits      | 64 bits optional | 8 bits              | 16 bits | -   |

**Table 19. Password identifier**

| Password identifier | Password |
|---------------------|----------|
| 10h                 | EAS/AFI  |

**Table 20. Response format when Error\_flag set**

| SOF | Flags  | Error code | CRC16   | EOF |
|-----|--------|------------|---------|-----|
| -   | 8 bits | 8 bits     | 16 bits | -   |

**Table 21. Response format when Error\_flag NOT set**

| SOF | Flags  | CRC16   | EOF |
|-----|--------|---------|-----|
| -   | 8 bits | 16 bits | -   |

#### 9.4.3.5 INVENTORY READ

**Command code = A0h**

When receiving the INVENTORY READ request, the ICODE SLIX IC performs the same as the anticollision sequence, with the difference that instead of the UID and the DSFID, the requested memory content is re-transmitted from the ICODE SLIX IC.

If an error is detected, the ICODE SLIX IC remains silent.

If the Option flag is set to logic 0, n blocks of data are re-transmitted. If the Option flag is set to 1, n blocks of data and the part of the UID which is not part of the mask are re-transmitted.

The request contains:

- Flags
- INVENTORY READ command code
- IC manufacturer code

- AFI (if AFI flag set)
- Mask length
- Mask value (if mask length > 0)
- First block number to be read
- Number of blocks to be read
- CRC 16

Table 22. Request format

| SOF | Flags  | INVENTORY READ | IC Mfg code | AFI             | Mask length | Mask value   | First block number | Number of blocks | CRC16   | EOF |
|-----|--------|----------------|-------------|-----------------|-------------|--------------|--------------------|------------------|---------|-----|
| -   | 8 bits | 8 bits         | 8 bits      | 8 bits optional | 8 bits      | 0 to 64 bits | 8 bits             | 8 bits           | 16 bits | -   |

The Inventory\_flag must be set to logic 1.

The meaning of flags 5 to 8 is in accordance with table 5 in ISO/IEC 15693-3.

The number of blocks in the request is one less than the number of blocks that the ICODE SLIX IC returns in its response.

If the Option flag in the request is set to logic 0 the response contains:

Table 23. Response format: Option flag logic 0

| SOF | Flags  | Data               | CRC16   | EOF |
|-----|--------|--------------------|---------|-----|
| -   | 8 bits | Block length       | 16 bits | -   |
|     |        | Repeated as needed |         |     |

The ICODE SLIX IC reads the requested block(s) and sends back their value in the response. The mechanism and timing of the INVENTORY READ command performs the same as the INVENTORY command which is described in clause 8 of ISO/IEC 15693-3.

If the Option flag in the request is set to logic 1, the response contains:

Table 24. Response format: Option flag logic 1

| SOF | Flags  | Rest of UID which is not part of the mask and slot number | Data               | CRC16   | EOF |
|-----|--------|-----------------------------------------------------------|--------------------|---------|-----|
| -   | 8 bits | 0 to 64 bit                                               | Block length       | 16 bits | -   |
|     |        | Multiple of 8 bits                                        | Repeated as needed |         |     |

The ICODE SLIX IC reads the requested block(s) and sends back their value in the response. Additionally the bytes of the UID, which are not parts of the mask and the slot number in case of 16 slots, are returned. Instead of padding with zeros up to the next byte boundary, the corresponding bits of the UID are returned. The mechanism and timing of the INVENTORY READ command perform the same as the INVENTORY command which is described in clause 8 of ISO/IEC 15693-3.

**Remark:** The number of bits of the re-transmitted UID can be calculated as follows:

- 16 slots: 60 bits (bit 64 to bit 4) - mask length rounded up to the next byte boundary
- 1 slot: 64 bits - mask length rounded up to the next byte boundary

**Remark:** If the sum of first block number and number of blocks exceeds the total available number of user blocks, the number of transmitted blocks is less than the requested number of blocks, which means that the last returned block is the highest available user block, followed by the 16-bit CRC and the EOF.

Example: mask length = 30 bits

Returned: bit 64 to bit 4 (30 bits) = 30 gives 4 bytes

**Table 25. Example: mask length = 30**

| Byte 0                                  | Byte 1 | Byte 2 | Byte 3 | Byte 4         | Byte 5 | Byte 6 | Byte 7 | UID                          |
|-----------------------------------------|--------|--------|--------|----------------|--------|--------|--------|------------------------------|
| mask value including padding with zeros |        |        |        | -              |        |        |        | transmitted by interrogator  |
|                                         |        |        |        | returned value |        |        |        | transmitted by ICODE SLIX IC |

#### 9.4.3.6 FAST INVENTORY READ

**Command code = A1h**

When receiving the FAST INVENTORY READ command the ICODE SLIX IC behaves the same as the INVENTORY READ command with the following exceptions:

The data rate in the direction ICODE SLIX IC to the interrogator is twice that defined in ISO/IEC 15693-3 depending on the Datarate\_flag 53 kbit (high data rate) or 13 kbit (low data rate).

The data rate from the interrogator to the ICODE SLIX IC and the time between the rising edge of the EOF from the interrogator to the ICODE SLIX IC remain unchanged (stay the same as defined in ISO/IEC 15693-3).

In the ICODE SLIX IC to the interrogator direction, only the single subcarrier mode is supported.

#### 9.4.3.7 SET EAS

**Command code = A2h**

The SET EAS command enables the EAS mode if the EAS mode is not locked. If the EAS mode is password protected the EAS password has to be first transmitted with the SET PASSWORD command.

The timing of the command is write alike.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

**Table 26. Request format**

| SOF | Flags  | SET EAS | IC Mfg code | UID                 | CRC16   | EOF |
|-----|--------|---------|-------------|---------------------|---------|-----|
| -   | 8 bits | 8 bits  | 8 bits      | 64 bits<br>optional | 16 bits | -   |

Table 27. Response format when Error\_flag set

| SOF | Flags  | Error code | CRC16   | EOF |
|-----|--------|------------|---------|-----|
| -   | 8 bits | 8 bits     | 16 bits | -   |

Table 28. Response format when Error\_flag NOT set

| SOF | Flags  | CRC16   | EOF |
|-----|--------|---------|-----|
| -   | 8 bits | 16 bits | -   |

#### 9.4.3.8 RESET EAS

Command code = A3h

The RESET EAS command disables the EAS mode if the EAS mode is not locked. If the EAS mode is password protected the EAS password has to be first transmitted with the SET PASSWORD command.

The timing of the command is write alike.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

Table 29. Request format

| SOF | Flags  | RESET EAS | IC Mfg code | UID                 | CRC16   | EOF |
|-----|--------|-----------|-------------|---------------------|---------|-----|
| -   | 8 bits | 8 bits    | 8 bits      | 64 bits<br>optional | 16 bits | -   |

Table 30. Response format when Error\_flag set

| SOF | Flags  | Error code | CRC16   | EOF |
|-----|--------|------------|---------|-----|
| -   | 8 bits | 8 bits     | 16 bits | -   |

Table 31. Response format when Error\_flag NOT set

| SOF | Flags  | CRC16   | EOF |
|-----|--------|---------|-----|
| -   | 8 bits | 16 bits | -   |

#### 9.4.3.9 LOCK EAS

Command code = A4h

The LOCK EAS command locks the current state of the EAS mode and the EAS ID. If the EAS mode is password protected the EAS password has to be first transmitted with the SET PASSWORD command.

The timing of the command is write alike.

Option 0 (Option flag not set) is supported.

Option 1 (Option flag set) is supported.

Table 32. Request format

| SOF | Flags  | LOCK EAS | IC Mfg code | UID                 | CRC16   | EOF |
|-----|--------|----------|-------------|---------------------|---------|-----|
| -   | 8 bits | 8 bits   | 8 bits      | 64 bits<br>optional | 16 bits | -   |

Table 33. Response format when Error\_flag set

| SOF | Flags  | Error code | CRC16   | EOF |
|-----|--------|------------|---------|-----|
| -   | 8 bits | 8 bits     | 16 bits | -   |

Table 34. Response format when Error\_flag NOT set

| SOF | Flags  | CRC16   | EOF |
|-----|--------|---------|-----|
| -   | 8 bits | 16 bits | -   |

#### 9.4.3.10 EAS ALARM

Command code = A5h

If the EAS mode is enabled, the EAS sequence is returned from the ICODE SLIX IC.

Table 35. Request format

| SOF | Flags  | EAS ALARM | IC Mfg code | UID              | CRC16   | EOF |
|-----|--------|-----------|-------------|------------------|---------|-----|
| -   | 8 bits | 8 bits    | 8 bits      | 64 bits optional | 16 bits | -   |

If an error is detected the ICODE SLIX IC remains silent.

Table 36. Response format

| SOF | Flags  | EAS sequence | CRC16   | EOF |
|-----|--------|--------------|---------|-----|
| -   | 8 bits | 256 bits     | 16 bits | -   |

EAS sequence (starting with the LSB, which is transmitted first; read from left to right):

```

11110100 11001101 01000110 00001110 10101011 11100101 00001001 11111110
00010111 10001101 00000001 00011100 01001011 10000001 10010010 01101110
01000001 01011011 01011001 01100001 11110110 11110101 11010001 00001101
10001111 00111001 10001011 01001000 10100101 01001110 11101100 11110111

```

If the EAS mode is disabled the ICODE SLIX IC remains silent.

#### 9.4.3.11 PASSWORD PROTECT EAS/AFI

Command code = A6h

The PASSWORD PROTECT EAS/AFI command enables the password protection for EAS and/or AFI if the EAS/AFI password is first transmitted with the SET PASSWORD command.

Option flag set to logic 0: EAS will be password protected.

Option flag set to logic 1: AFI will be password protected.

Both password protections (AFI and EAS) can be enabled separately.

**Remark:** Independent of the Option flag, this write-alike command will be executed like a write command with Option flag 0 (Option flag not set).

Once the EAS/AFI password protection is enabled, it is not possible to change back to unprotected EAS and/or AFI.

The timing of the command is write alike (as write command with Option flag 0).

Table 37. Request format

| SOF | Flags  | PASSWORD<br>PROTECT EAS/AFI | IC Mfg code | UID              | CRC16   | EOF |
|-----|--------|-----------------------------|-------------|------------------|---------|-----|
| -   | 8 bits | 8 bits                      | 8 bits      | 64 bits optional | 16 bits | -   |

Table 38. Response format when Error\_flag set

| SOF | Flags  | Error code | CRC16   | EOF |
|-----|--------|------------|---------|-----|
| -   | 8 bits | 8 bits     | 16 bits | -   |

Table 39. Response format when Error\_flag NOT set

| SOF | Flags  | CRC16   | EOF |
|-----|--------|---------|-----|
| -   | 8 bits | 16 bits | -   |

## 9.5 Error handling

### 9.5.1 Transmission errors

According to ISO/IEC 15693 the label IC will not respond if a transmission error (CRC, bit coding, bit count, wrong framing) is detected and will silently wait for the next correct received command.

### 9.5.2 Not supported commands or options

If the received command or option is not supported, the behavior of the label IC depends on the addressing mechanism.

#### 9.5.2.1 Non Addressed Mode

The label IC remains silent.

#### 9.5.2.2 Addressed or Selected Mode

The addressed or selected label IC responds with the error code "0Fh" (error with no information given or error code is not supported).

If the Inventory flag or the Protocol Extension flag is set, the label IC will not respond if the command or option is not supported.

### 9.5.3 Parameter out of range

#### 9.5.3.1 Read commands

If the sum of the first block number and the number of blocks exceeds the total available number of user blocks, the number of transmitted blocks is less than the requested number of blocks, which means that the last returned block is the highest available user block, followed by the 16-bit CRC and the EOF.

#### 9.5.3.2 Write and lock commands

If the address of a block to be written does not exist or a block to be written is locked, the behaviour of the label IC depends on the addressing mechanism.

#### Non Addressed Mode

- The label IC remains silent and aborts the command without writing anything.

**Addressed or Selected Mode**

- The addressed or selected label IC responds with the error code “0Fh”(error with no information given or error code is not supported).

**9.6 Data integrity**

Following mechanisms are implemented in the contactless communication link between interrogator and label to ensure very reliable data transmission:

- 16-bit CRC per block
- Bit count checking
- Bit coding to distinguish between logic 1, logic 0, and no information
- Channel monitoring (protocol sequence and bit stream analysis)

**9.7 RF interface**

The definition of the RF interface is according to the standard ISO/IEC 15693-2 and ISO/IEC 15693-3.

**10. Limiting values**

**Table 40. Limiting values (Wafer)**<sup>[1][2]</sup>

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

| Symbol              | Parameter                       | Conditions       | Min              | Max  | Unit |
|---------------------|---------------------------------|------------------|------------------|------|------|
| T <sub>stg</sub>    | storage temperature             |                  | -55              | +125 | °C   |
| P <sub>tot</sub>    | total power dissipation         |                  | -                | 125  | mW   |
| T <sub>j</sub>      | junction temperature            |                  | -40              | +85  | °C   |
| I <sub>i(max)</sub> | maximum input current           | LA to LB; peak   | <sup>[3]</sup> - | ±60  | mA   |
| I <sub>I</sub>      | input current                   | LA to LB; RMS    | -                | 30   | mA   |
| V <sub>ESD</sub>    | electrostatic discharge voltage | Human body model | <sup>[4]</sup> - | ±2   | kV   |

- [1] Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the operating conditions and electrical characteristics sections of this specification is not implied.
- [2] This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maxima.
- [3] The voltage between LA and LB is limited by the on-chip voltage limitation circuitry (corresponding to parameter I<sub>I</sub>).
- [4] For ESD measurement, the IC was mounted in a CDIP8 package.

## 11. Characteristics

### 11.1 Memory characteristics

Table 41. EEPROM characteristics

| Symbol               | Parameter       | Conditions                                       | Min    | Typ | Max | Unit  |
|----------------------|-----------------|--------------------------------------------------|--------|-----|-----|-------|
| $t_{\text{ret}}$     | retention time  | $T_{\text{amb}} \leq 55\text{ }^{\circ}\text{C}$ | 50     | -   | -   | year  |
| $N_{\text{endu(W)}}$ | write endurance |                                                  | 100000 | -   | -   | cycle |

### 11.2 Interface characteristics

Table 42. Interface characteristics

Typical ratings are not guaranteed. The values listed are at room temperature.

| Symbol                        | Parameter                 | Conditions                 | Min        | Typ   | Max    | Unit          |
|-------------------------------|---------------------------|----------------------------|------------|-------|--------|---------------|
| $f_i$                         | input frequency           |                            | [1] 13.553 | 13.56 | 13.567 | MHz           |
| $V_{i(\text{RMS})\text{min}}$ | minimum RMS input voltage | operating read/write       | 1.5        | -     | 1.7    | V             |
| $P_{i(\text{min})}$           | minimum input power       | operating                  | [2] -      | 40    | -      | $\mu\text{W}$ |
| $C_i$                         | input capacitance         | between LA and LB          | [3]        |       |        |               |
|                               |                           | SL2S2002FUD<br>SL2S2002FTB | 22.3       | 23.5  | 24.7   | pF            |
|                               |                           | SL2S2102FUD<br>SL2S2102FTB | 92         | 97    | 102    | pF            |

[1] Bandwidth limitation ( $\pm 7\text{ kHz}$ ) according to ISM band regulations.

[2] Including losses in the resonant capacitor and rectifier.

[3] Measured with an HP4285A LCR meter at 13.56 MHz and 2 V RMS.

## 12. Marking

### 12.1 Marking SOT1122

Table 43. Marking SOT1122

| Type number | Marking code |
|-------------|--------------|
| SL2S2002FTB | 20           |
| SL2S2102FTB | 21           |

13. Package outline

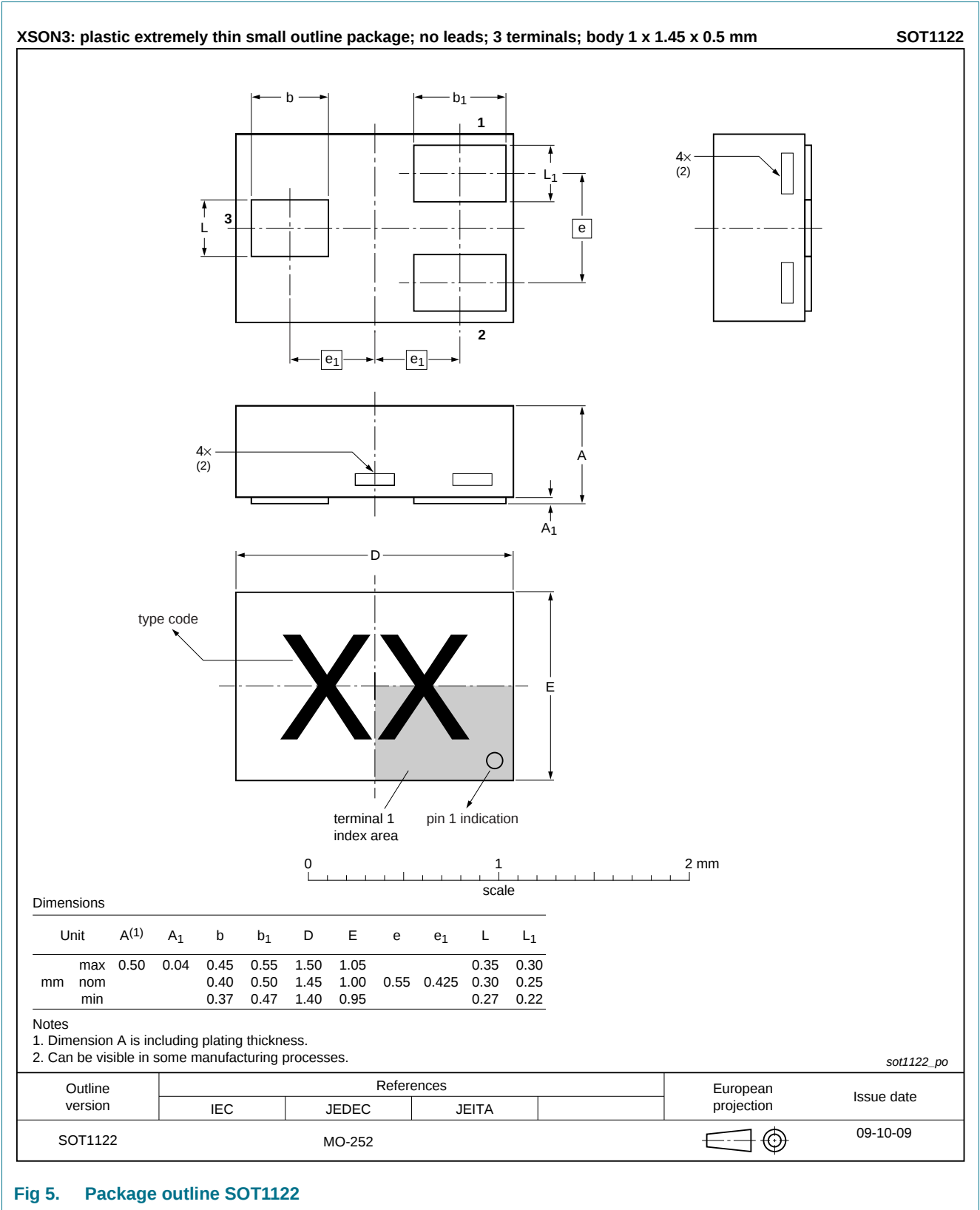
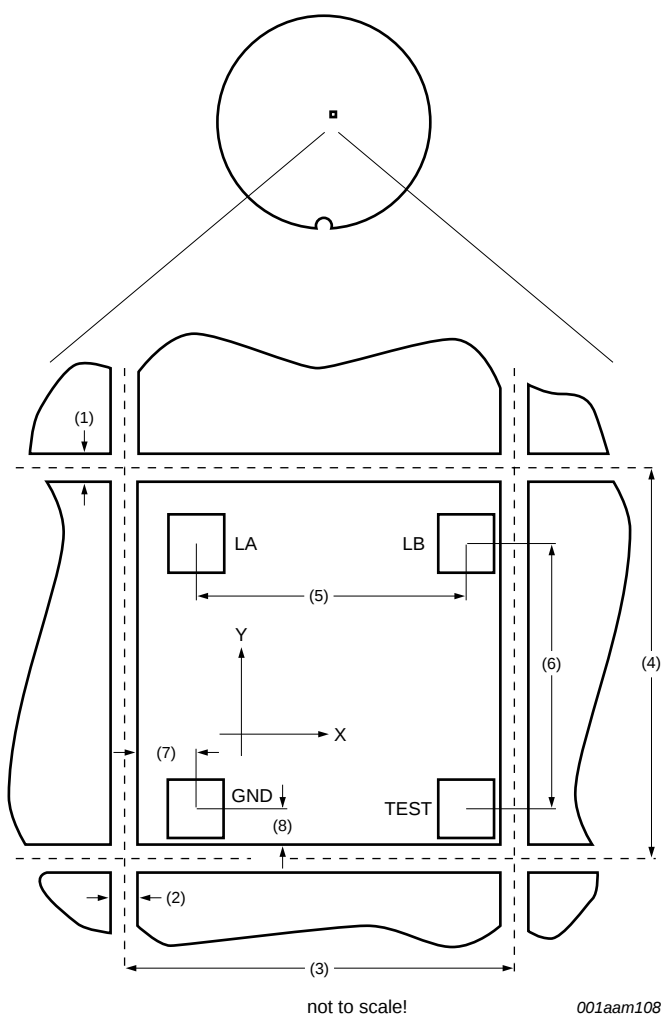


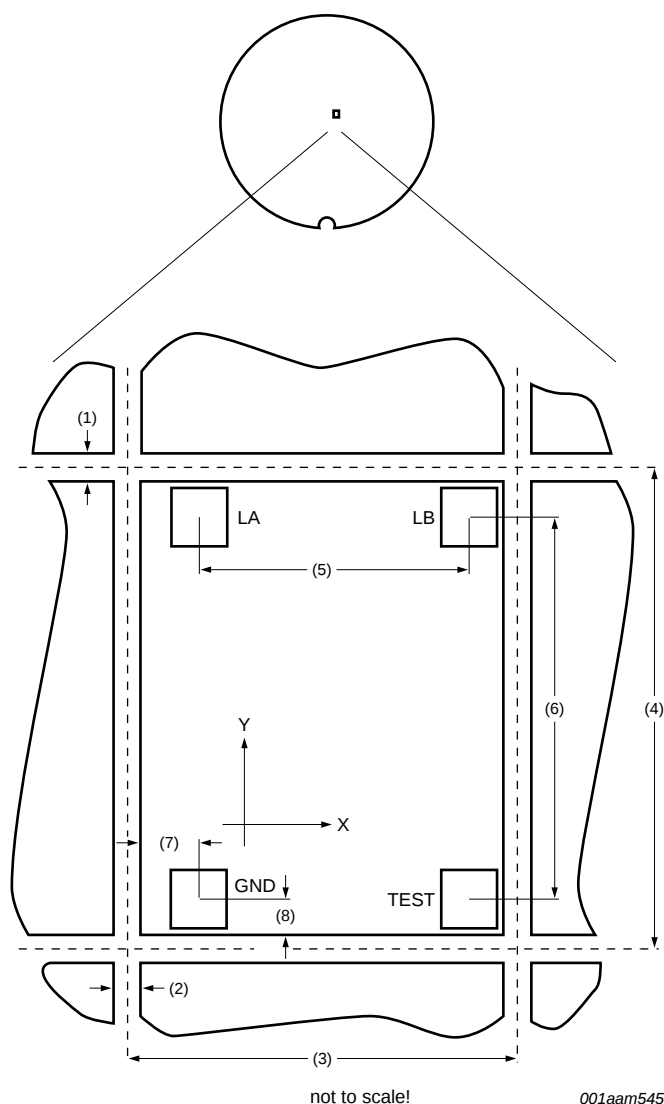
Fig 5. Package outline SOT1122

## 14. Bare die outline



- (1) X-scribe line width: 15  $\mu\text{m}$
- (2) Y-scribe line width: 15  $\mu\text{m}$
- (3) Chip step, X-length: 535  $\mu\text{m}$
- (4) Chip step, Y-length: 499  $\mu\text{m}$
- (5) Bump to bump distance X (LA - LB): 400  $\mu\text{m}$
- (6) Bump to bump distance Y (LB - TEST): 360  $\mu\text{m}$
- (7) Distance bump to nitride edge X: 75  $\mu\text{m}$
- (8) Distance bump to nitride edge Y: 45  $\mu\text{m}$
- Bump size X  $\times$  Y: 60  $\mu\text{m} \times$  60  $\mu\text{m}$

**Fig 6. Wafer SL2S2002FUD bare die layout**



- (1) X-scribe line width: 15  $\mu\text{m}$
- (2) Y-scribe line width: 15  $\mu\text{m}$
- (3) Chip step, X-length: 535  $\mu\text{m}$
- (4) Chip step, Y-length: 622  $\mu\text{m}$
- (5) Bump to bump distance X (LA - LB): 400  $\mu\text{m}$
- (6) Bump to bump distance Y (LB - TEST): 517  $\mu\text{m}$
- (7) Distance bump to nitride edge X: 75  $\mu\text{m}$
- (8) Distance bump to nitride edge Y: 45  $\mu\text{m}$
- Bump size X  $\times$  Y: 60  $\mu\text{m} \times$  60  $\mu\text{m}$

**Fig 7. Wafer SL2S2102FUD bare die layout**

## 15. Abbreviations

Table 44. Abbreviations

| Acronym | Description                                         |
|---------|-----------------------------------------------------|
| AFI     | Application Family Identifier                       |
| CRC     | Cyclic Redundancy Check                             |
| DSFID   | Data Storage Format Identifier                      |
| EAS     | Electronic Article Surveillance                     |
| EEPROM  | Electrically Erasable Programmable Read Only Memory |
| EOF     | End Of Frame                                        |
| IC      | Integrated Circuit                                  |
| LCR     | Inductance, Capacitance, Resistance                 |
| LSB     | Least Significant Byte/Bit                          |
| MSB     | Most Significant Byte/Bit                           |
| RF      | Radio Frequency                                     |
| SOF     | Start Of Frame                                      |
| UID     | Unique Identifier                                   |

## 16. References

- [1] **ISO Standard** — ISO/IEC 15693 - Identification cards - Contactless integrated circuit cards - Vicinity cards.
- [2] **ISO Standard** — ISO/IEC 15693-2 -Identification cards - Contactless integrated circuit cards - Vicinity cards - Part 2: Air interface and initialization.
- [3] **ISO Standard** — ISO/IEC 15693-3 -Identification cards - Contactless integrated circuit cards - Vicinity cards - Part 3: Anticollision and transmission protocol.
- [4] **ISO Standard** — ISO/IEC 18000-3 - Information technology - Radio frequency identification for item management - Part 3: Parameters for air interface communications at 13.56 MHz.
- [5] **ISO Standard** — ISO/IEC 7816-6 - Identification cards - Integrated circuit cards - Part 6: Interindustry data elements for interchange.
- [6] **General specification for 8" wafer on UV-tape with electronic fail die marking** — Delivery type description – BL-ID document number: 1093\*\*1.

1. \*\* ... document version number

## 17. Revision history

**Table 45. Revision history**

| Document ID            | Release date                                                                                                                                                                                           | Data sheet status      | Change notice | Supersedes             |
|------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------|---------------|------------------------|
| SL2S2002_SL2S2102 v3.3 | 20120823                                                                                                                                                                                               | Product data sheet     | -             | SL2S2002_SL2S2102 v3.2 |
| Modifications:         | <ul style="list-style-type: none"> <li>Security level changed into "COMPANY PUBLIC"</li> </ul>                                                                                                         |                        |               |                        |
| SL2S2002_SL2S2102 v3.2 | 20110110                                                                                                                                                                                               | Product data sheet     | -             | SL2S2002_SL2S2102 v3.1 |
| Modifications:         | <ul style="list-style-type: none"> <li>Type numbers SL2S2002FTB and SL2S2102FTB added</li> <li>Section 6 "Pinning information", Section 12 "Marking" and Section 13 "Package outline" added</li> </ul> |                        |               |                        |
| SL2S2002_SL2S2102 v3.1 | 20100908                                                                                                                                                                                               | Product data sheet     | -             | SL2S2002 v3.0          |
| Modifications:         | <ul style="list-style-type: none"> <li>Added type number SL2S2102</li> <li>Document layout updated</li> <li>Table 43: symbols and parameter descriptions updated</li> </ul>                            |                        |               |                        |
| SL2S2002 v3.0          | 20100527                                                                                                                                                                                               | Product data sheet     | -             | 178020                 |
| 178020                 | 20100430                                                                                                                                                                                               | Preliminary data sheet | -             | 178010                 |
| 178010                 | 20100205                                                                                                                                                                                               | Objective data sheet   | -             | -                      |

## 18. Legal information

### 18.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition                                                                            |
|-----------------------------------|-------------------------------|---------------------------------------------------------------------------------------|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

### 18.2 Definitions

**Draft** — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

**Short data sheet** — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

**Product specification** — The information and data provided in a Product data sheet shall define the specification of the product as agreed between NXP Semiconductors and its customer, unless NXP Semiconductors and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the NXP Semiconductors product is deemed to offer functions and qualities beyond those described in the Product data sheet.

### 18.3 Disclaimers

**Limited warranty and liability** — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

**Right to make changes** — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

**Suitability for use** — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors and its suppliers accept no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

**Applications** — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

**Limiting values** — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

**Terms and conditions of commercial sale** — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

**No offer to sell or license** — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

**Export control** — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

**Quick reference data** — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

**Non-automotive qualified products** — Unless this data sheet expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the product for such automotive applications, use and specifications, and (b)

whenever customer uses the product for automotive applications beyond NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

**Translations** — A non-English (translated) version of a document is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

## 18.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

**ICODE and I-CODE** — are trademarks of NXP B.V.

## 19. Contact information

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

## 20. Tables

|           |                                         |    |           |                                                |    |
|-----------|-----------------------------------------|----|-----------|------------------------------------------------|----|
| Table 1.  | Ordering information                    | 3  | Table 24. | Response format: Option flag logic 1           | 17 |
| Table 2.  | Pin description SOT1122                 | 4  | Table 25. | Example: mask length = 30                      | 18 |
| Table 3.  | Bonding pad description                 | 6  | Table 26. | Request format                                 | 18 |
| Table 4.  | Wafer specification                     | 7  | Table 27. | Response format when Error_flag set            | 19 |
| Table 5.  | Memory organization                     | 10 | Table 28. | Response format when Error_flag NOT set        | 19 |
| Table 6.  | Unique identifier                       | 10 | Table 29. | Request format                                 | 19 |
| Table 7.  | Request format                          | 14 | Table 30. | Response format when Error_flag set            | 19 |
| Table 8.  | Response format when Error_flag set     | 14 | Table 31. | Response format when Error_flag NOT set        | 19 |
| Table 9.  | Response format when Error_flag NOT set | 14 | Table 32. | Request format                                 | 19 |
| Table 10. | Request format                          | 14 | Table 33. | Response format when Error_flag set            | 20 |
| Table 11. | Password Identifier                     | 14 | Table 34. | Response format when Error_flag NOT set        | 20 |
| Table 12. | Response format when Error_flag set     | 14 | Table 35. | Request format                                 | 20 |
| Table 13. | Response format when Error_flag NOT set | 15 | Table 36. | Response format                                | 20 |
| Table 14. | Request format                          | 15 | Table 37. | Request format                                 | 21 |
| Table 15. | Password identifier                     | 15 | Table 38. | Response format when Error_flag set            | 21 |
| Table 16. | Response format when Error_flag set     | 15 | Table 39. | Response format when Error_flag NOT set        | 21 |
| Table 17. | Response format when Error_flag NOT set | 15 | Table 40. | Limiting values (Wafer) <a href="#">[1][2]</a> | 22 |
| Table 18. | Request format                          | 16 | Table 41. | EEPROM characteristics                         | 23 |
| Table 19. | Password identifier                     | 16 | Table 42. | Interface characteristics                      | 23 |
| Table 20. | Response format when Error_flag set     | 16 | Table 43. | Marking SOT1122                                | 23 |
| Table 21. | Response format when Error_flag NOT set | 16 | Table 44. | Abbreviations                                  | 27 |
| Table 22. | Request format                          | 17 | Table 45. | Revision history                               | 28 |
| Table 23. | Response format: Option flag logic 0    | 17 |           |                                                |    |

## 21. Figures

|        |                                                                 |    |
|--------|-----------------------------------------------------------------|----|
| Fig 1. | Block diagram of ICODE SLIX                                     | 3  |
| Fig 2. | Pin configuration for SOT1122                                   | 4  |
| Fig 3. | Wafer SL2S2002FUD layout and pin configuration for the bare die | 5  |
| Fig 4. | Wafer SL2S2102FUD layout and pin configuration for the bare die | 6  |
| Fig 5. | Package outline SOT1122                                         | 24 |
| Fig 6. | Wafer SL2S2002FUD bare die layout                               | 25 |
| Fig 7. | Wafer SL2S2102FUD bare die layout                               | 26 |

## 22. Contents

|          |                                           |          |           |                                   |           |
|----------|-------------------------------------------|----------|-----------|-----------------------------------|-----------|
| <b>1</b> | <b>General description</b> . . . . .      | <b>1</b> | 9.4.3.5   | INVENTORY READ                    | 16        |
| 1.1      | Contactless energy and data transfer      | 1        | 9.4.3.6   | FAST INVENTORY READ               | 18        |
| 1.2      | Anticollision                             | 1        | 9.4.3.7   | SET EAS                           | 18        |
| 1.3      | Security and privacy aspects              | 1        | 9.4.3.8   | RESET EAS                         | 19        |
| <b>2</b> | <b>Features and benefits</b> . . . . .    | <b>2</b> | 9.4.3.9   | LOCK EAS                          | 19        |
| 2.1      | ICODE SLIX RF interface (ISO/IEC 15693)   | 2        | 9.4.3.10  | EAS ALARM                         | 20        |
| 2.2      | EEPROM                                    | 2        | 9.4.3.11  | PASSWORD PROTECT EAS/AFI          | 20        |
| 2.3      | Security                                  | 2        | 9.5       | Error handling                    | 21        |
| <b>3</b> | <b>Applications</b> . . . . .             | <b>2</b> | 9.5.1     | Transmission errors               | 21        |
| <b>4</b> | <b>Ordering information</b> . . . . .     | <b>3</b> | 9.5.2     | Not supported commands or options | 21        |
| <b>5</b> | <b>Block diagram</b> . . . . .            | <b>3</b> | 9.5.2.1   | Non Addressed Mode                | 21        |
| <b>6</b> | <b>Pinning information</b> . . . . .      | <b>4</b> | 9.5.2.2   | Addressed or Selected Mode        | 21        |
| <b>7</b> | <b>Wafer layout</b> . . . . .             | <b>5</b> | 9.5.3     | Parameter out of range            | 21        |
| 7.1      | Bonding pad description                   | 6        | 9.5.3.1   | Read commands                     | 21        |
| <b>8</b> | <b>Mechanical specification</b> . . . . . | <b>7</b> | 9.5.3.2   | Write and lock commands           | 21        |
| 8.1      | Wafer specification                       | 7        |           | Non Addressed Mode                | 21        |
| 8.1.1    | Fail die identification                   | 8        |           | Addressed or Selected Mode        | 22        |
| 8.1.2    | Map file distribution                     | 8        | 9.6       | Data integrity                    | 22        |
| <b>9</b> | <b>Functional description</b> . . . . .   | <b>9</b> | 9.7       | RF interface                      | 22        |
| 9.1      | Block description                         | 9        | <b>10</b> | <b>Limiting values</b>            | <b>22</b> |
| 9.2      | Memory organization                       | 9        | <b>11</b> | <b>Characteristics</b>            | <b>23</b> |
| 9.2.1    | Unique identifier                         | 10       | 11.1      | Memory characteristics            | 23        |
| 9.2.2    | Configuration of delivered ICs            | 11       | 11.2      | Interface characteristics         | 23        |
| 9.3      | Communication principle                   | 11       | <b>12</b> | <b>Marking</b>                    | <b>23</b> |
| 9.4      | Supported commands                        | 11       | 12.1      | Marking SOT1122                   | 23        |
| 9.4.1    | Mandatory commands                        | 11       | <b>13</b> | <b>Package outline</b>            | <b>24</b> |
| 9.4.1.1  | INVENTORY                                 | 11       | <b>14</b> | <b>Bare die outline</b>           | <b>25</b> |
| 9.4.1.2  | STAY QUIET                                | 11       | <b>15</b> | <b>Abbreviations</b>              | <b>27</b> |
| 9.4.2    | Optional commands                         | 12       | <b>16</b> | <b>References</b>                 | <b>27</b> |
| 9.4.2.1  | READ SINGLE BLOCK                         | 12       | <b>17</b> | <b>Revision history</b>           | <b>28</b> |
| 9.4.2.2  | WRITE SINGLE BLOCK                        | 12       | <b>18</b> | <b>Legal information</b>          | <b>29</b> |
| 9.4.2.3  | LOCK BLOCK                                | 12       | 18.1      | Data sheet status                 | 29        |
| 9.4.2.4  | READ MULTIPLE BLOCKS                      | 12       | 18.2      | Definitions                       | 29        |
| 9.4.2.5  | SELECT                                    | 12       | 18.3      | Disclaimers                       | 29        |
| 9.4.2.6  | RESET TO READY                            | 12       | 18.4      | Trademarks                        | 30        |
| 9.4.2.7  | WRITE AFI                                 | 12       | <b>19</b> | <b>Contact information</b>        | <b>30</b> |
| 9.4.2.8  | LOCK AFI                                  | 13       | <b>20</b> | <b>Tables</b>                     | <b>31</b> |
| 9.4.2.9  | WRITE DSFID                               | 13       | <b>21</b> | <b>Figures</b>                    | <b>31</b> |
| 9.4.2.10 | LOCK DSFID                                | 13       | <b>22</b> | <b>Contents</b>                   | <b>32</b> |
| 9.4.2.11 | GET SYSTEM INFORMATION                    | 13       |           |                                   |           |
| 9.4.2.12 | GET MULTIPLE BLOCK SECURITY STATUS        | 13       |           |                                   |           |
| 9.4.3    | Custom commands                           | 13       |           |                                   |           |
| 9.4.3.1  | GET RANDOM NUMBER                         | 13       |           |                                   |           |
| 9.4.3.2  | SET PASSWORD                              | 14       |           |                                   |           |
| 9.4.3.3  | WRITE PASSWORD                            | 15       |           |                                   |           |
| 9.4.3.4  | LOCK PASSWORD                             | 16       |           |                                   |           |

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

© NXP B.V. 2012.

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

Date of release: 23 August 2012  
178033